

PRELIMINARY AMENDMENT
DIV. OF 09/889,739, FILED JULY 20, 2001

AMENDMENTS TO THE SPECIFICATION

Please replace the present title with the following rewritten title:

A METHOD OF MANUFACTURING DISCRETE ELECTRONIC COMPONENTS

Amend the specification by inserting before the first line the sentence:

This is a divisional of Application No. 09/889,739 filed July 20, 2001; the disclosure of which is incorporated herein by reference.

Page 1, between the title and the first paragraph, insert and center

BACKGROUND OF THE INVENTION

Page 2, between the third and fourth full paragraphs, insert and center

SUMMARY OF THE INVENTION

Page 3, between the second and third full paragraphs, insert and center

BRIEF DESCRIPTION OF THE DRAWING

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Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure.

A METHOD OF MANUFACTURING DISCRETE ELECTRONIC COMPONENTS

The manufacturing method for components of the inductive type, in particular inductance coils, transformers or antennae, consists in making by micro-machining simultaneously on a first substrate made of magnetic material a plurality of first parts (1) connected to each other by connecting elements (2) or a connecting support, inserting on the arms (8a, 8b, 8c) of these first parts (1) a printed multi-layered plate (4, 5) having openings for the arms and metal windings ending in at least two contact pads (7a, 7b), in placing and securing a second substrate made of magnetic material on the first substrate and the plate, said second substrate having undergone micro-machining to obtain second parts (13) complementary to the first parts. These second parts are connected to each other by connecting elements or a connecting support. Then, the components are separated and, in a particular implementation, the contact pads arranged on tongues (16, 18) of said plate are folded against a base (9) of the core or of the magnetic circuit to allow form a surface mounting (SMD).device.

Figure 5